

Maximum Ratings @T_A = 25°C unless otherwise specified

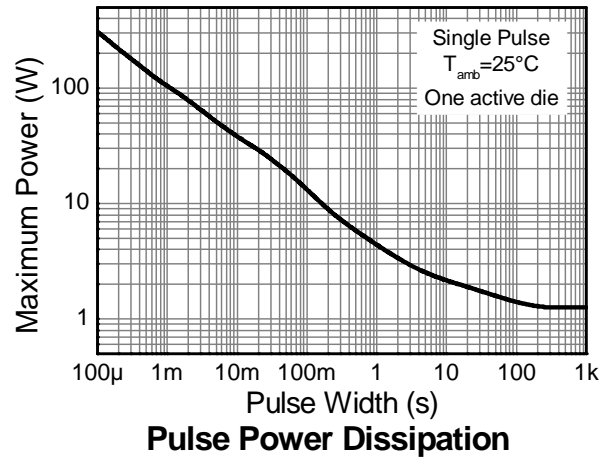
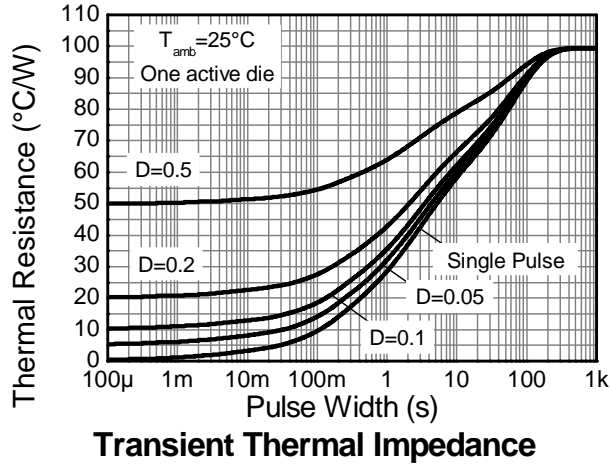
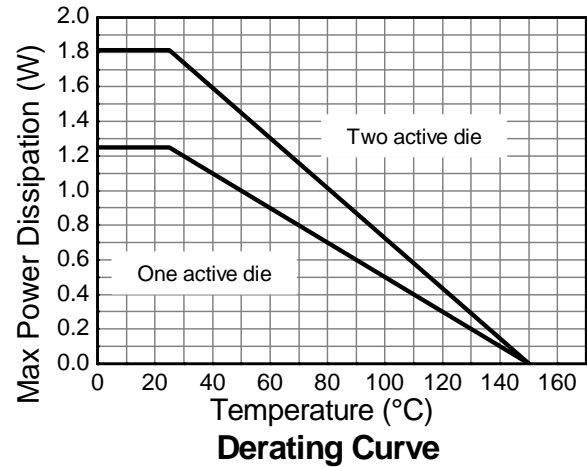
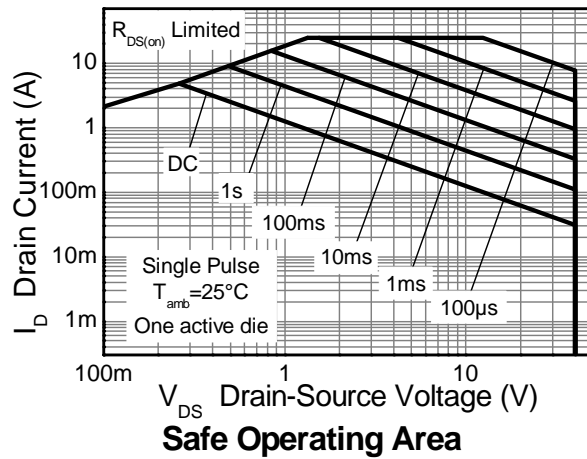
Characteristic			Symbol	Value	Unit
Drain-Source voltage			V _{DSS}	40	V
Gate-Source voltage	(Note 2)		V _{GS}	±20	V
Single Pulsed Avalanche Energy	(Note 9)		E _{AS}	27	mJ
Single Pulsed Avalanche Current	(Note 9)		I _{AS}	15.25	A
Continuous Drain current	V _{GS} = 10V	(Note 4)	I _D	6.3	A
		T _A = 70°C (Note 4)		5.0	
		(Note 3)		4.8	
Pulsed Drain current	V _{GS} = 10V	(Note 5)	I _{DM}	24.8	A
Continuous Source current (Body diode)		(Note 4)	I _S	3.3	A
Pulsed Source current (Body diode)		(Note 5)	I _{SM}	24.8	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation Linear derating factor	(Notes 3 & 6)	P _D	1.25	W mW/°C
			10.0	
	(Notes 3 & 7)		1.80	
			14.3	
Thermal Resistance, Junction to Ambient	(Notes 4 & 6)	R _{θJA}	2.14	°C/W
	(Notes 3 & 6)		100	
	(Notes 3 & 7)		70	
Thermal Resistance, Junction to Lead	(Notes 4 & 6)	R _{θJL}	58	°C/W
	(Notes 6 & 8)		55	
Operating and storage temperature range		T _J , T _{STG}	-55 to 150	°C

- Notes:
- AEC-Q101 V_{GS} maximum is ±16V.
 - For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - Same as note (3), except the device is measured at t ≤ 10 sec.
 - Same as note (3), except the device is pulsed with D = 0.02 and pulse width 300μs. The pulse current is limited by the maximum junction temperature.
 - For a dual device with one active die.
 - For a device with two active die running at equal power.
 - Thermal resistance from junction to solder-point (at the end of the drain lead).
 - UIS in production with L = 100μH, V_{DD} = 40V.

Thermal Characteristics

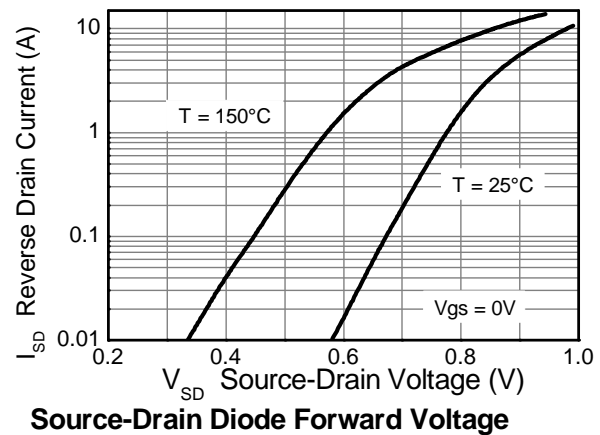
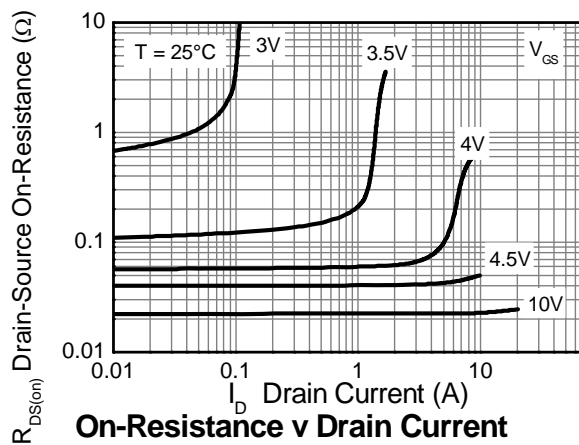
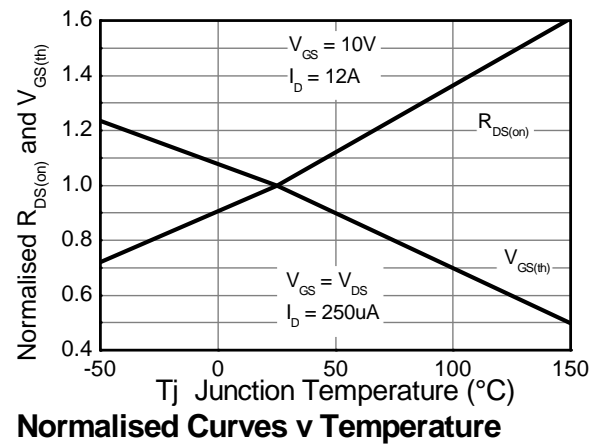
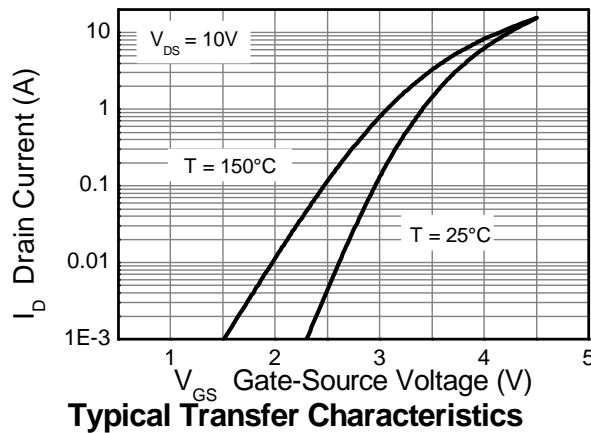
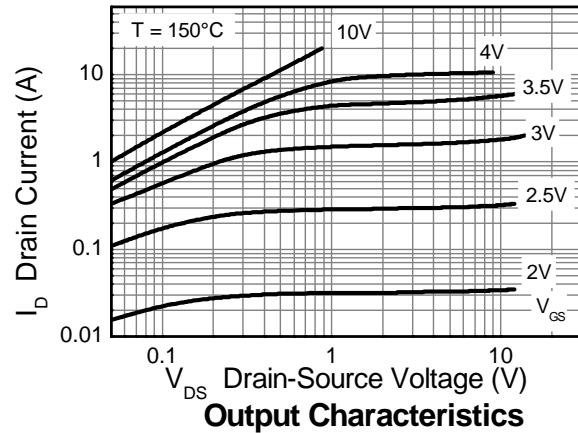
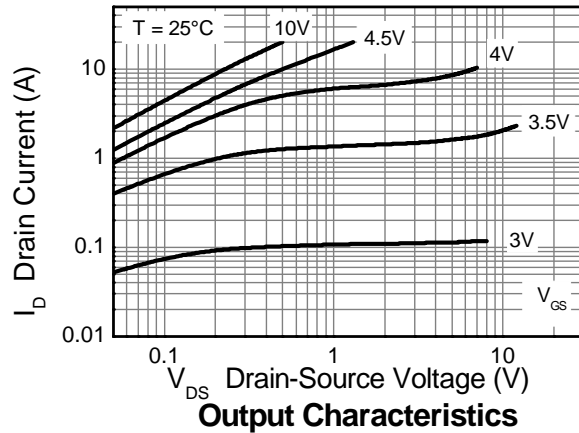


Electrical Characteristics @T_A = 25°C unless otherwise specified

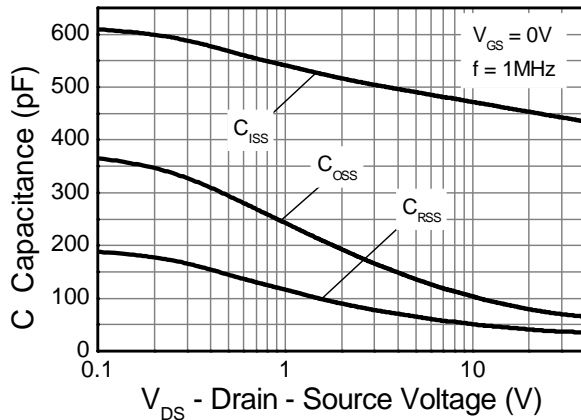
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	40	—	—	V	I _D = 250μA, V _{GS} = 0V	
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 40V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	I _D = 250μA, V _{DS} = V _{GS}	
Static Drain-Source On-Resistance (Note 10)	R _{DS (ON)}	—	0.023	0.034	Ω	V _{GS} = 10V, I _D = 6A	
			0.039	0.059		V _{GS} = 4.5V, I _D = 5A	
Forward Transconductance (Notes 10 & 11)	g _{fs}	—	20.5	—	S	V _{DS} = 15V, I _D = 6A	
Diode Forward Voltage (Note 10)	V _{SD}	—	0.87	1.1	V	I _S = 6A, V _{GS} = 0V	
Reverse recovery time (Note 11)	t _{rr}	—	11.2	—	ns	I _S = 2A, di/dt= 100A/μs	
Reverse recovery charge (Note 11)	Q _{rr}	—	4.8	—	nC		
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	C _{iss}	—	453	—	pF	V _{DS} = 20V, V _{GS} = 0V f = 1MHz	
Output Capacitance	C _{oss}	—	79.1	—	pF		
Reverse Transfer Capacitance	C _{rss}	—	40.5	—	pF		
Total Gate Charge (Note 12)	Q _g	—	4.9	8	nC	V _{GS} = 4.5V	V _{DS} = 20V I _D = 6A
Total Gate Charge (Note 12)	Q _g	—	10	18	nC	V _{GS} = 10V	
Gate-Source Charge (Note 12)	Q _{gs}	—	1.8	—	nC		
Gate-Drain Charge (Note 12)	Q _{gd}	—	2.4	—	nC		
Turn-On Delay Time (Note 12)	t _{D(on)}	—	2.7	—	ns	V _{DD} = 20V, V _{GS} = 10V I _D = 1A, R _G ≅ 6.0Ω	
Turn-On Rise Time (Note 12)	t _r	—	2.7	—	ns		
Turn-Off Delay Time (Note 12)	t _{D(off)}	—	14	—	ns		
Turn-Off Fall Time (Note 12)	t _f	—	6	—	ns		

Notes: 10. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
11. For design aid only, not subject to production testing.
12. Switching characteristics are independent of operating junction temperatures.

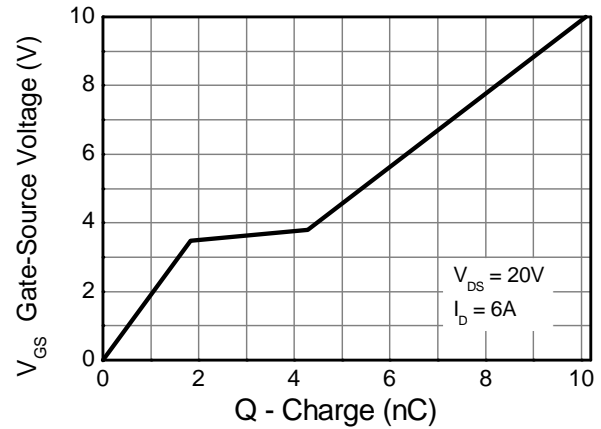
Typical Characteristics



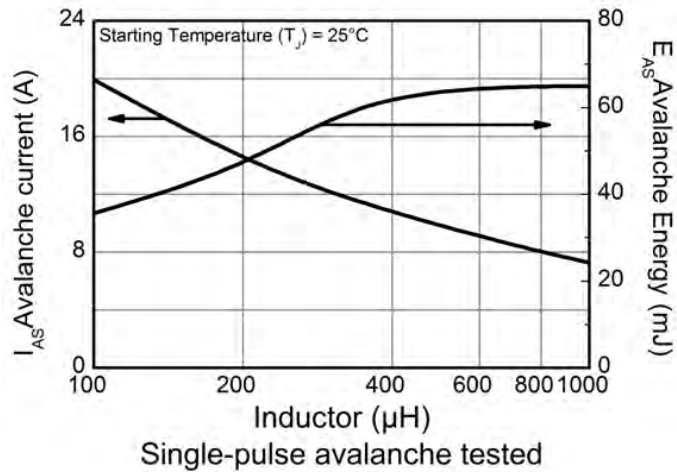
Typical Characteristics – continued



Capacitance v Drain-Source Voltage

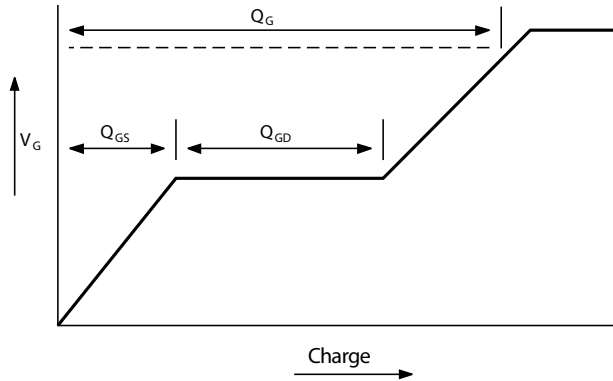


Gate-Source Voltage v Gate Charge

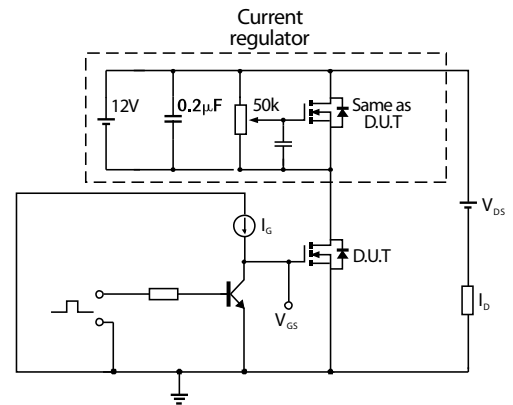


Single-pulse avalanche tested

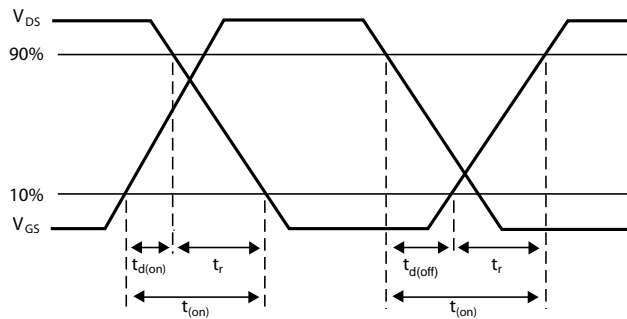
Test Circuits



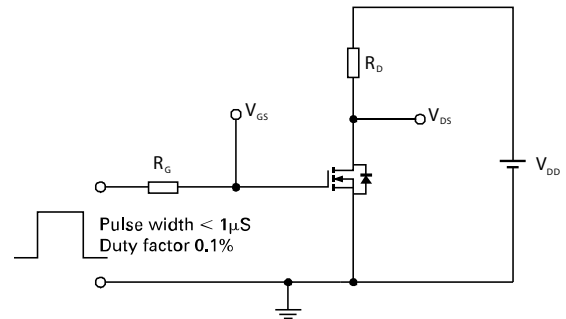
Basic gate charge waveform



Gate charge test circuit

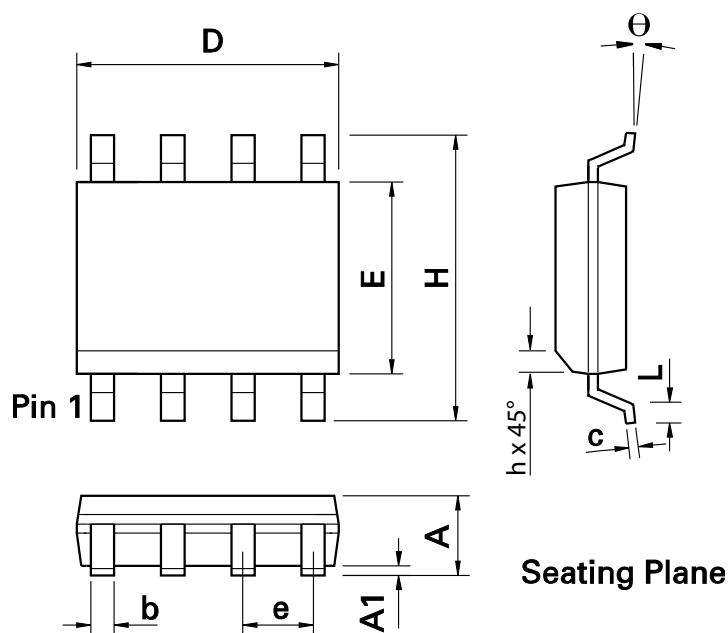


Switching time waveforms



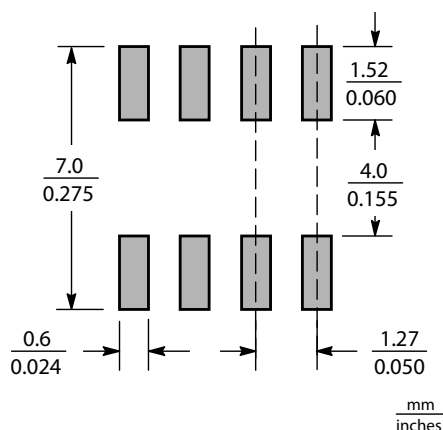
Switching time test circuit

Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.053	0.069	1.35	1.75	e	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51
D	0.189	0.197	4.80	5.00	c	0.008	0.010	0.19	0.25
H	0.228	0.244	5.80	6.20	θ	0°	8°	0°	8°
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

Suggested Pad Layout



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